

SURFACE-MOUNTING SUBSTRATE AND STRUCTURE COMPRISING  
SUBSTRATE AND PART MOUNTED ON THE SUBSTRATE

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ABSTRACT OF THE DISCLOSURE

10 A surface-mounting substrate, for mounting thereon a  
part such as a semiconductor device, which comprises a  
core substrate, a plurality of layers of patterned wiring  
lines, which are separated from each other by an  
insulation layer interposed therebetween, vias piercing  
15 through the insulation layer to connect the wiring lines  
at the adjacent layers to each other, and a layer of  
connecting terminals to mount a part on the surface-  
mounting substrate, each of the connecting terminals  
connecting with the wiring line at the outermost layer of  
wiring lines, wherein the connecting terminal is filled  
20 in an outermost insulation layer provided at the surface  
of the surface-mounting substrate, and has a surface  
exposed at substantially the same level as the level of  
the surface of the outermost insulation layer. A  
structure comprising a surface-mounting substrate and a  
25 part mounted thereon, which comprises, as the substrate  
used, the surface-mounting substrate of the invention, is  
also disclosed.